

C L A I M S

1 1. A method of calibrating modification of optical devices,
2 comprising the steps of providing a mask with a predetermined pattern,
3 projecting radiation through the mask so as to form a patterned projected
4 image; and comparing a pattern of the projected image with a pattern of the
5 mask to determine deviations of the projected image from the image of the
6 mask.

1 2. A method as defined in claim 1, wherein said comparing
2 includes comparing a size of the projected image with the size of the image
3 on the mask.

1 3. A method as defined in claim 1, wherein said providing the
2 mask includes providing a mask which has at least two fields each having a
3 plurality of features spaced from one another in one direction so that the
4 directions of spacing of the features in said two fields are transverse to one
5 another.

1 4. A method as defined in claim 3, wherein said features in
2 each of said field are evenly spaced from one another.

1 5. A method as defined in claim 3, wherein said features in
2 each of said fields are parallel to one another.

1 6. A method as defined in claim 3; and further comprising
2 arranging the mask so that said features of at least one of said fields are
3 aligned with a principal axis of the optical device.

1 7. A method as defined in claim 3, wherein said features are
2 arranged so that a spacing between the features of one of said fields is
3 different from the spacing of said features of the other of said fields.

1 8. A method as defined in claim 1; and further comprising
2 moving an article on which the image is projected relative to the optical
3 device so as to produce a plurality of images with a plurality of patterns, said
4 comparing includes comparing the plurality of patterns of the plurality of
5 images with the pattern of the mask.

10 9. A method as defined in claim 1, wherein said obtaining of
11 the projected image includes providing a substrate, projecting the pattern
12 through the mask on the substrate, and obtaining the projected image on the
13 substrate.

1 10. A method as defined in claim 1, wherein said obtaining of
2 projected image includes passing the radiation through the mask and
3 obtaining an electronic image with a pattern, said comparing includes
4 comparing the pattern of the electronic image with the pattern of the mask.

1 11. A method as defined in claim 1, wherein said comparing
2 includes comparing a deviation of a magnification of the pattern and the
3 image relative to the pattern of the mask from a standard deviation.

1 12. A method as defined in claim 1, wherein said providing
2 includes forming a mask by an optical source producing an interference
3 pattern corresponding to the desired pattern of the mask.

1 13. A method as defined in claim 1, wherein said providing
2 includes producing the mask by an optical source which generates an
3 interference pattern and acts on a chemical substance to cause etching of
4 corresponding areas of the mask so as to produce the desired pattern of the
5 mask.